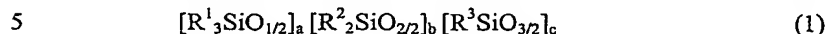


## CLAIMS

1. A curable silicone composition comprising:

(A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings:



where  $R^1$ ,  $R^2$ , and  $R^3$  are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of  $R^3$  are aryl groups;  $a + b + c = 1$ ; on average, "a" satisfies the following condition:  $0 \leq a \leq 0.8$ ; on average, "b" satisfies the following condition:  $0 \leq b \leq 0.8$ ; and, on average, "c" satisfies the following condition:  $0.2 \leq c \leq 1.0$ ;

- 10 (B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups; and

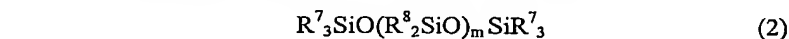
(C) a curing accelerator.

2. The curable silicone composition of Claim 1, further comprising a filler (D).

3. The curable silicone composition of Claim 1 or Claim 2, where component (A) is liquid.

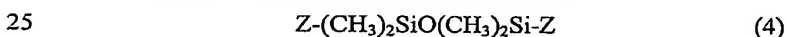
- 15 4. The curable silicone composition of Claim 1 or Claim 2, where in the siloxane unit formula (1)  $0 < a \leq 0.8$ ; and  $b = 0$ .

5. The curable silicone composition of Claim 1 or Claim 2, where component (B) is an organopolysiloxane represented by the following formula (2):



where  $R^7$  and  $R^8$  may be the same or different and represent univalent organic groups of which, at least two are univalent organic groups having phenolic hydroxyl groups; and "m" is an integer having a value of 0 to 1000].

6. The curable silicone composition of Claim 1 or Claim 2, where component (B) is an organopolysiloxane represented by the following formula (4):



where Z is 3-(m-hydroxyphenyl)propyl group.

7. The curable silicone composition of Claim 1 or Claim 2, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).

- 30 8. The curable silicone composition of Claim 1 or Claim 2, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.

9. The curable silicone composition of Claim 1 or Claim 2, which is in a liquid or a paste-like form.

10. A cured product obtained by curing the curable silicone composition according to any of Claims from 1 to 9.

- 35 11. Use of the cured product according to Claim 10 for connection or sealing of elements in an electric or electronic device.